

IN THE SPECIFICATION

Please amend the Specification on Page 8, as follows:

“FIG. 2 is a view showing a circuit configuration of the IC card 10;

FIG. 3 is a plan view of an IC module 11 constituting the IC card 10;

FIG. 4 is a sectional side view showing the structure of an IC mounted portion of the IC module 11;

FIG. 5 is a sectional side view showing whole of the IC module 11;

FIG. 6 is a sectional side view of an IC card, showing one example of the structure of a core layer 12 having the IC module 11 disposed therein;

FIG. 7 is a sectional side view of an IC card, showing another example of the structure of the core layer 12; and

FIG. 8 is a sectional side view of an IC card, showing still another example of the structure of the core layer 12;

FIG. 9 is a table illustrating materials of inner and outer cores of a core layer and their respective thicknesses as utilized in a plurality of experimental examples; and

FIG. 10 is a table illustrating experimental examples of a structure of the core layer, results of evaluations of printing properties and printing properties after a heat resistance test, and a generation of halogen gas during an incineration.”

Description of the Preferred Embodiments

Hereinbelow, preferred embodiments of the present invention will be described with reference to the drawings.

FIG. 1 shows one example of the structure of a non-contact IC card 10 according to an embodiment of the present invention. A core layer 12 including a plurality of